**Fully-Automatic wafer mounter equipped with a pre-cut tape mounting function in a vacuum environment.**

- By using our unique vacuum control method, wafer mounting is performed without any contact with wafer surface.
- By adopting the non-contact wafer backside handling method, contamination of wafer is prevented.

**Power Supply**
- Voltage: AC200-230V ±10% (AC190-253V)
- Frequency: 50/60Hz
- Phase: single phase
- Power consumption: 4.0kW

**Air Supply**
- Air pressure: 0.6-0.8MPa
- Air consumption: >800L/min (ANR)

**Vacuum Supply**
- Vacuum pressure: >-80kPa
- Ultimate Pressure: 1.0Pa
- Pumping Speed: >250L/min

**Applicable Wafer Size**
- 200mm (*300mm currently in development)

**Size**
- Width: 2,203mm
- Depth: 3,092mm
- Height: 1,800mm
  (excluding the signal tower and protruding parts)

**Weight**
- 2,600kg

**UPH**
- 20 wafers/hour

The above processing capacity is based on following conditions:
- Wafer: 200mm diameter non-polished mirror wafer
- Ring frame: for 200mm wafer
- Dicing tape: D-184 from LINTEC

**Outline**

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- By adopting the non-contact wafer backside handling method, contamination of wafer is prevented.

**Options**
- Host Communication Function (Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
- Vision System (Wafer ID Reader & Barcode Attachment System)
- Dicing Tape In-line Pre-cutting

**Suitable Tape**
- Dicing tape: Adwill D series, G series

**External View**